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PATENT

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Suzushi KIMURA, et al.

Serial No.: 09/719,631

Filed: February 12, 2001

For: MODULE COMPONENT AND METHOD
OF MANUFACTURING THE SAME

)
) Group Art Unit: 2827

)
) Examiner: K. CUNEO

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AMENDMENT UNDER 37 C.F.R. § 1.111

Hon. Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action dated March 28, 2002, having a shortened statutory period for response set to expire June 28, 2002, please amend the above-identified application as follows:

IN THE DRAWINGS:

Please amend Figs. 1, 2, 3(b), 4(a)-9(g) and 11(a)-12(b) as indicated on the marked-up copy thereof enclosed herewith. As shown, the figures have been amended to correct the cross-hatching in the sectional views and to include the legend "Prior Art" on Figs 12(a) and 12(b). Formal drawings incorporating the changes will be submitted

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once the proposed amendments have been approved.

IN THE SPECIFICATION:

Please replace the paragraph beginning at page 4, lines 11-25, with the following rewritten paragraph:

B1 --Fig. 1(a) is a sectional view at line I-I' showing a schematic structure of a module component in embodiment 1 of the invention, and Fig. 1(b) is a top view of the component. In the diagrams, reference numeral 1 denotes a resin substrate. In the substrate, chip resistors 2, chip capacitors 3, and other chip components are inserted into penetration holes having the nearly same hole shapes as chip components, and their end electrodes and circuit wirings 4a and 4b formed on both sides of resin substrate 1 are electrically coupled to compose a desired electric circuit. They are held and reinforced between first auxiliary substrate 5 and second auxiliary substrate 6. IC chip 7 and electronic components 8 that are hardly reduced in size are mounted on first auxiliary substrate 5 and are electrically coupled to wiring circuit 4c and further to circuit wiring 4a through conductor filling in through-holes 9. Reference numeral 7a denotes a molding resin, 10 denotes an external electrode terminal on module component 11.--

IN THE CLAIMS:

Please cancel claim 3, without prejudice.

Please amend claims 1, 4-8 and 10-12, and add new claims 31-35 as follows:

- B2 1. (Twice Amended) A module component comprising:
a substrate made of resin having a plurality of penetration holes, said plurality of